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<b>PRODUCT / PROCESS CHANGE NOTICE (PCN)</b>							
PCN Number: 12-28		Means of Distinguishing Changed Devices:					
Date Issued: October	24, 2012		<ul> <li>Product Mark</li> <li>Back Mark</li> <li>Date Code</li> <li>Other: Shipment with the new packing</li> </ul>				
Product(s) Affected: S	ee below						
Manufacturing Location							
Date Effective: Jan 24	<b>, 2013</b>		quantities will begin Jan 24, 2013				
Contact: Li Hua			Attachment: 🗌 Yes; 🖾 No				
Title: Quality Manage	r						
Phone: ( <b>8621) 6119578</b>	5 Fax: (8621)64	852181					
EMails: PCN_PDN@p	· · ·						
Description and Purpose of Change:			Die Technology				
	C		Wafer Fabrication				
Pericom would like to			Assembly Process				
packing quathtity (MPC	) and minmum or						
(MOQ) nave been adju	sted accordingly.						
Pericom P/N	Existing MPQ and MOQ	New MPQ and MOQ	Manufacturing Site				
PT7C433833UEX	3000	4000	Data Sheet				
PI4ULS5V102UEX	3000	4000	Other: Packing				
PT7C4337UEX	3000	4000					
PT7C4563UEX	3000	4000					
PI3A412ZHEX	5000	3500					
PI4ULS5V4555ZHEX	5000	3500					
	5000						
PI5A3158BZAEX	3000	3500					
(MOQ) have been adjust Pericom P/N PT7C433833UEX PI4ULS5V102UEX PT7C4337UEX PT7C4563UEX PI3A412ZHEX	Consenquently the consendent of the consendent of the constant	New MPQ and MOQ 4000 4000 4000 3500	Data Sheet				

	PERICO			The Complete Interface Solution			
Sen	niconductor Corpor	ration					
Customer A	cknowledgement of	Receipt:					
Customer:							
Name:	_						
Title:	-						
Date:	_						
eMail:	_						
Phone:							
Fax:	_						
Approval for shipments prior to effective date     Customer Comments (Optional):							
Pericom Inte	ernal Use Only:						
Location:	PSC	🛛 PTI	PSE-TW	PSE-SD			
PSETW PC	N: N/A						